L	Hits	Search Text	DB	Time stamp
Number			110000	2002/11/12
4	344	<pre>(((bottom or (back adj side)) with (tape or adhesive) with (wafer or substrate)) same (dic\$3 or cut\$4)) and ((wafer or substrate) with (bottom or (back adj side) with etch\$3))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 14:29
5	323	<pre>(((bottom or (back adj side)) with (tape or adhesive) with (wafer or substrate)) same (dic\$3 or cut\$4)) same ((wafer or substrate) with (bottom or (back adj side) with etch\$3))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 14:29
6	64	<pre>((((bottom or (back adj side)) with (tape or adhesive) with (wafer or substrate)) same (dic\$3 or cut\$4)) same ((wafer or substrate) with (bottom or (back adj</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 17:20
7	28	side) with etch\$3))) and 438/\$3.ccls. (((((bottom or (back adj side)) with (tape or adhesive) with (wafer or substrate)) same (dic\$3 or cut\$4)) same ((wafer or substrate) with (bottom or (back adj side) with etch\$3))) and 438/\$3.ccls.) and @ad<20001205	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 17:31
79	8	uv with tape with needle	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 16:31
80	11	(uv with tape) same needle	USPAT; US-PGPUB; EPO; JPO;	2003/11/13 16:33
81	10	(ultraviolet with tape) same needle	DERWENT USPAT; US-PGPUB; EPO; JPO;	2003/11/13 16:39
82	72	(ultraviolet with adhesive) same needle	DERWENT USPAT; US-PGPUB; EPO; JPO;	2003/11/13 16:40
83	6	((ultraviolet with adhesive) same needle) same dic\$3	DERWENT USPAT; US-PGPUB; EPO; JPO;	2003/11/13 17:03
84	7	(transfer adj tape) with (dicing adj tape)	DERWENT USPAT; US-PGPUB; EPO; JPO;	2003/11/13 19:04
85	1389	(transfer adj tape) with (adhesive)	DERWENT USPAT; US-PGPUB; EPO; JPO;	2003/11/13 17:30
86	6	((transfer adj tape) with (adhesive)) with dicing	DERWENT USPAT; US-PGPUB; EPO; JPO;	2003/11/13 17:05
87	6	((transfer adj tape) with (adhesive)) same dicing	DERWENT USPAT; US-PGPUB; EPO; JPO;	2003/11/13 17:05
88	11	(transfer adj tape) with dicing	DERWENT USPAT; US-PGPUB; EPO; JPO;	2003/11/13 17:06
89	7	(transfer adj tape) same (dicing adj tape)	DERWENT USPAT; US-PGPUB; EPO; JPO;	2003/11/13 17:28
90	15	((transfer adj tape) with (adhesive)) and 438/\$3.ccls.	DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 17:30

			****	0000/01/11
91	0	(pickup adj tape) same (dicing adj tape)	USPAT; US-PGPUB; EPO; JPO;	2003/11/13 17:28
			DERWENT	
92	2	(pickup adj tape) and (dicing adj tape)	USPAT;	2003/11/13
92	2	(pickup adj tape) and (dicing adj tape)	US-PGPUB;	17:28
-			EPO; JPO;	
			DERWENT	
93	236	(dicing adj tape) with (adhesive)	USPAT;	2003/11/13
			US-PGPUB;	17:30
			EPO; JPO;	
94	70	((dicing adj tape) with (adhesive)) and	DERWENT USPAT;	2003/11/13
34	'0	438/\$3.ccls.	US-PGPUB;	17:31
1		,	EPO; JPO;	
			DERWENT	
95	24	(((dicing adj tape) with (adhesive)) and	USPAT;	2003/11/13
		438/\$3.ccls.) and @ad<20001205	US-PGPUB;	17:31
			EPO; JPO; DERWENT	
96	6	(releas\$3 adj tape) with (dicing adj	USPAT;	2003/11/13
	"	tape)	US-PGPUB;	19:05
		· · · · ·	EPO; JPO;	
			DERWENT	
-	6	(dicing adj tape) same (transfer tape)	USPAT;	2003/11/13
		same (etched adj ports)	US-PGPUB; EPO; JPO;	11:52
			DERWENT	
-	6	(dicing adj tape) with (through adj hole)	USPAT;	2003/11/12
1		with backside	US-PGPUB;	18:10
			EPO; JPO;	
	1 12	 ("4791075" "4907065" "5150196"	DERWENT USPAT	2003/11/12
-	13	("4791075" "4907065" "5150196" "5323051" "5362681" "5435876"	OSPAI	18:09
ļ		"5610431" "5824177" "5831162"		
		"6106735" "6109113" "6210514"		
		"6410360").PN.		2002/11/12
-	6	(dicing adj tape) same (through adj hole) same backside	USPAT; US-PGPUB;	2003/11/12
		Same DackSide	EPO; JPO;	10.11
			DERWENT	
-	12	(dicing adj tape) and ((hole or via or	USPAT;	2003/11/12
		open\$3 or interconnect) with (substrate	US-PGPUB;	18:39
		or wafer)) and (transfer adj tape)	EPO; JPO;	
_	194	dicing adj tape) and ((hole or via or	DERWENT USPAT;	2003/11/12
	194	open\$3 or interconnect) with (substrate	US-PGPUB;	18:40
		or wafer))	EPO; JPO;	
			DERWENT	
-	53	(dicing adj tape) same ((hole or via or	USPAT;	2003/11/12
1		open\$3 or interconnect) with (substrate or wafer))	US-PGPUB; EPO; JPO;	18:42
		Or warer)	DERWENT	
-	20	((dicing adj tape) same ((hole or via or	USPAT;	2003/11/12
		open\$3 or interconnect) with (substrate	US-PGPUB;	19:00
1		or wafer))) and @ad<20001205	EPO; JPO;	
_	36	 (dicing adj tape) with wafer with	DERWENT USPAT;	2003/11/12
	26	(dicing adj tape) with waier with backside	US-PGPUB;	18:58
			EPO; JPO;	
			DERWENT	
-	148	tape with wafer with backside	USPAT;	2003/11/12
			US-PGPUB; EPO; JPO;	18:59
			DERWENT	
_	246	tape with (wafer or substrate) with	USPAT;	2003/11/12
		backside	US-PGPUB;	18:59
			EPO; JPO;	
			DERWENT	

				0000/11/75
-	1713		USPAT;	2003/11/12
		with (wafer or substrate) with backside	US-PGPUB;	19:00
			EPO; JPO;	
			DERWENT	2002/11/12
-	38		USPAT;	2003/11/12
		backside) and ((hole or open\$3 or via or	US-PGPUB; EPO; JPO;	19:00
		interconnect) with (wafer or substrate)	DERWENT	
		with backside)	USPAT;	2003/11/12
-	22	((tape with (wafer or substrate) with backside) and ((hole or open\$3 or via or	US-PGPUB;	19:00
		interconnect) with (wafer or substrate)	EPO; JPO;	1 19.00
		with backside)) and dic\$3	DERWENT	
	6		USPAT;	2003/11/12
-	•	backside) and ((hole or open\$3 or via or	US-PGPUB;	19:00
		interconnect) with (wafer or substrate)	EPO; JPO;	13.00
		with backside)) and dic\$3) and	DERWENT	
		@ad<20001205	DD1	
l _	2	5362681.pn.	USPAT;	2003/11/13
-		3302001.pm.	US-PGPUB;	11:56
			EPO; JPO;	
			DERWENT	
_	56	5362681.URPN.	USPAT	2003/11/13
				11:53
_	6315	((bottom or (back adj side)) with (tape	USPAT;	2003/11/13
	0313	or adhesive)) same (dic\$3 or cut\$4)	US-PGPUB;	11:57
	!		EPO; JPO;	
			DERWENT	ļ l
1_	469	((bottom or (back adj side)) with (tape	USPAT;	2003/11/13
		or adhesive) with (wafer or substrate))	US-PGPUB;	11:58
		same (dic\$3 or cut\$4)	EPO; JPO;	
		, , ,	DERWENT	
-	257327	(wafer or substrate) with (via hole	USPAT;	2003/11/13
		open\$3 interconnect)	US-PGPUB;	11:59
1			EPO; JPO;	
			DERWENT	
_	80	(((bottom or (back adj side)) with (tape	USPAT;	2003/11/13
		or adhesive) with (wafer or substrate))	US-PGPUB;	14:27
		same (dic\$3 or cut\$4)) same ((wafer or	EPO; JPO;	
		substrate) with (via hole open\$3	DERWENT	1
		interconnect))		
-	0	, , , , , , , , , , , , , , , , , , , ,	USPAT;	2003/11/13
		or adhesive) with (wafer or substrate))	US-PGPUB;	11:59
		same (dic\$3 or cut\$4)) same ((wafer or	EPO; JPO;	
		substrate) with (via hole open\$3	DERWENT	
		interconnect))) and 5362681.URPN.	IIGDAE :	2002/11/12
_	8		USPAT;	2003/11/13
		side)) with (tape or adhesive) with	US-PGPUB;	16:29
		(wafer or substrate)) same (dic\$3 or	EPO; JPO;	
	1	cut\$4))	DERWENT USPAT;	2003/11/13
-	1	007585.apn.	USPAT; US-PGPUB;	12:12
			EPO; JPO;	12.14
			DERWENT	
_	43	((((bottom or (back adj side)) with (tape	USPAT;	2003/11/13
-	1 43	or adhesive) with (wafer or substrate))	US-PGPUB;	12:12
		same (dic\$3 or cut\$4)) same ((wafer or	EPO; JPO;	
		substrate) with (via hole open\$3	DERWENT	1
		interconnect))) and @ad<20001205		
_	15	("4872825" "4933744" "5178957"	USPAT	2003/11/13
		"5497033" "5685885" "5730922"	1	12:35
		"5747101" "5761801" "5766979"		
		"5848467" "5866952" "5958995"		
		"5962608" "5971253" "6007407").PN.		